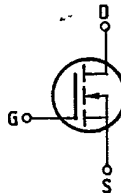


SIEMENS AKTIENGESELLSCHAFT

Main ratings

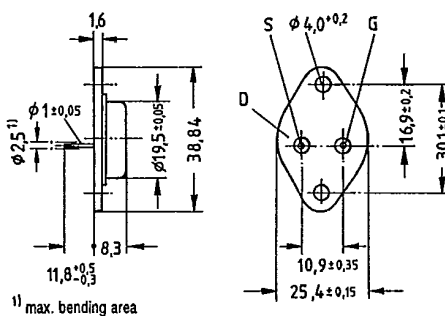
Drain-source voltage  $V_{DS} = 800$  V  
 Continuous drain current  $I_D = 3,4$  A  
 Drain-source on-resistance  $R_{DS(on)} = 3,0$   $\Omega$

N-Channel



Description SIPMOS, N-channel, enhancement mode  
 Case Metal case 3A2 in accordance with DIN 41872, or TO 204 AA (TO 3) in accordance with JEDEC.  
 Approx. weight 12 g

Type	Ordering code
BUZ 83 A	C67078-A1012-A3



1) max. bending area

Dimensions in mm

Maximum ratings

Description	Symbols	Ratings	Units	Conditions
Drain-source voltage	$V_{DS}$	800	V	
Drain-gate voltage	$V_{DGR}$	800	V	$R_{GS} = 20$ k $\Omega$
Continuous drain current	$I_D$	3,4	A	$T_C = 25$ °C
Pulsed drain current	$I_{Dpuls}$	11	A	$T_C = 25$ °C
Gate-source voltage	$V_{GS}$	$\pm 20$	V	
Max. power dissipation	$P_D$	78	W	$T_C = 25$ °C
Operating and storage temperature range	$T_{stg}$	-55... +150	°C	
DIN humidity category		C	-	DIN 40040
IEC climatic category		55/150/56	-	DIN IEC 68-1

Thermal resistance

Chip - case	$R_{th JC}$	$\leq 1,6$	K/W
Chip - ambient	$R_{th JA}$	$\leq 35$	K/W

520 Preferred Type

1102

B-05

SIEMENS AKTIENGESELLSCHAFT

**Electrical characteristics**

(at  $T_j = 25^\circ\text{C}$  unless otherwise specified)

Description	Symbol	Characteristics			Unit	Conditions
		min.	typ.	max.		

**Static ratings**

Drain-source breakdown voltage	$V_{(BR)DSS}$	800	—	—	V	$V_{GS} = 0V$ $I_D = 0,25mA$
Gate threshold voltage	$V_{GS(th)}$	2,1	3,0	4,0		$V_{DS} = V_{GS}$ $I_D = 1mA$
Zero gate voltage drain current	$I_{DSS}$	—	20	250	$\mu A$	$T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ $V_{DS} = 800V$ $V_{GS} = 0V$
Gate-source leakage current	$I_{GSS}$	—	10	100	nA	$V_{GS} = 20V$ $V_{DS} = 0V$
Drain-source on-resistance	$R_{DS(on)}$	—	2,7	3,0	$\Omega$	$V_{GS} = 10V$ $I_D = 1,7A$

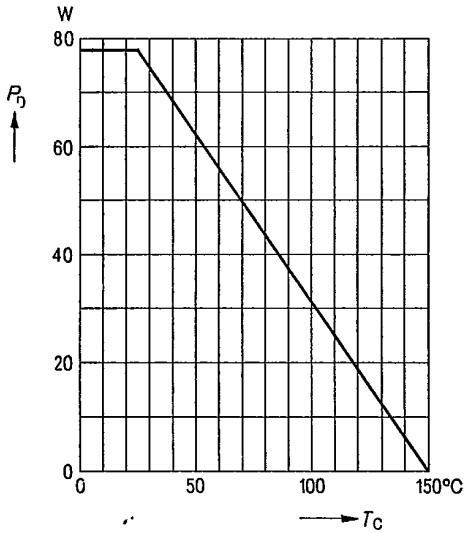
**Dynamic ratings**

Forward transconductance	$g_{fs}$	1,0	1,8	—	S	$V_{DS} = 25V$ $I_D = 1,7A$
Input capacitance	$C_{iss}$	—	1,6	2,1	nF	$V_{GS} = 0V$
Output capacitance	$C_{oss}$	—	90	150	pF	$V_{DS} = 25V$ $f = 1MHz$
Reverse transfer capacitance	$C_{rss}$	—	30	55		
Turn-on time $t_{on}$ ( $t_{on} = t_d(on) + t_r$ )	$t_d(on)$	—	30	45	ns	$V_{CC} = 30V$ $I_D = 2,3A$ $V_{GS} = 10V$ $R_{GS} = 50\Omega$
	$t_r$	—	40	60		
Turn-off time $t_{off}$ ( $t_{off} = t_d(off) + t_f$ )	$t_d(off)$	—	110	140		
	$t_f$	—	60	80		

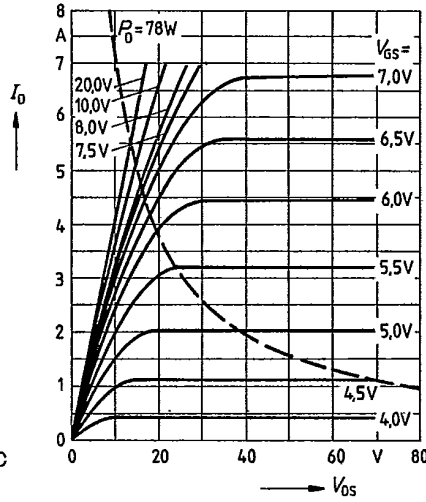
**Reverse diode**

Continuous reverse drain current	$I_{DR}$	—	—	3,4	A	$T_C = 25^\circ\text{C}$
Pulsed reverse drain current	$I_{DRM}$	—	—	13		
Diode forward on-voltage	$V_{SD}$	—	1,1	1,35	V	$I_F = 2 \times I_{DR}$ $V_{GS} = 0V, T_j = 25^\circ\text{C}$
Reverse recovery time	$t_{rr}$	—	1800	—	ns	$T_j = 25^\circ\text{C}$
Reverse recovery charge	$Q_{rr}$	—	12	—	$\mu C$	$I_F = I_{DR}$ $dI_F/dt = 100A/\mu s$ $V_R = 100V$

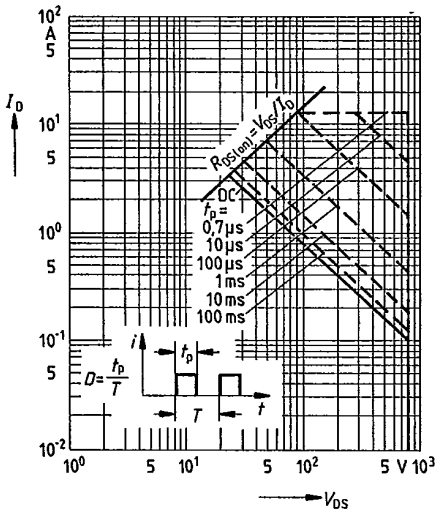
Power dissipation  $P_D = f(T_C)$



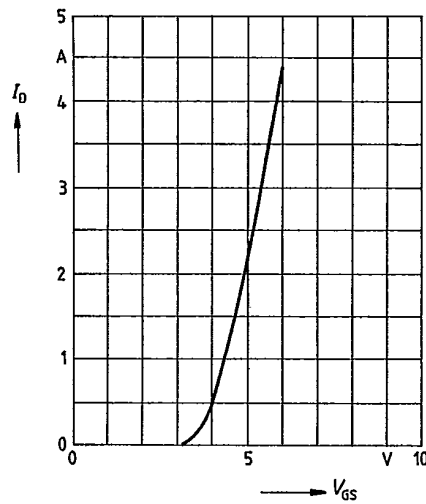
Typical output characteristics  $I_D = f(V_{DS})$   
parameter: 80  $\mu$ s pulse test,  
 $T_j = 25^\circ\text{C}$



Safe operating area  $I_D = f(V_{DS})$   
parameter:  $D = 0.01$ ,  $T_C = 25^\circ\text{C}$

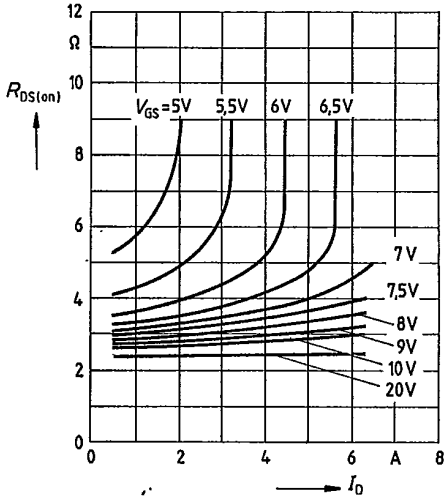


Typical transfer characteristic  $I_D = f(V_{GS})$   
parameter: 80  $\mu$ s pulse test,  
 $V_{DS} = 25\text{V}$ ,  $T_j = 25^\circ\text{C}$



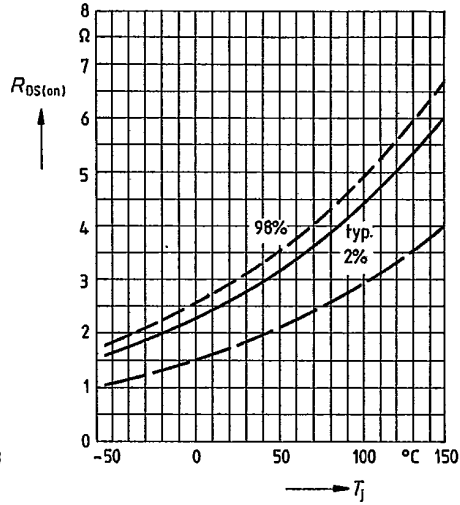
Typical drain-source on-state resistance

$R_{DS(on)} = f(I_D)$   
parameter:  $V_{GS}$ ;  $T_J = 25^\circ\text{C}$



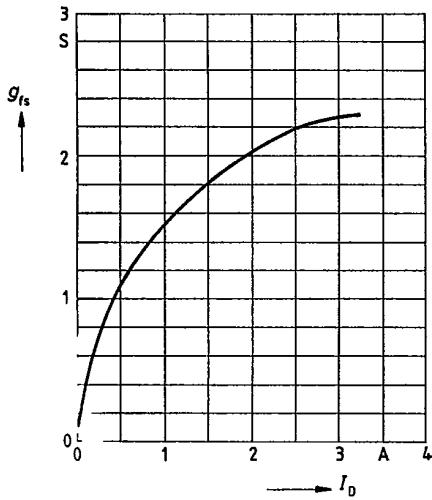
Drain-source on-state resistance

$R_{DS(on)} = f(T_J)$   
parameter:  $I_D = 1.7\text{A}$ ,  $V_{GS} = 10\text{V}$   
(spread)



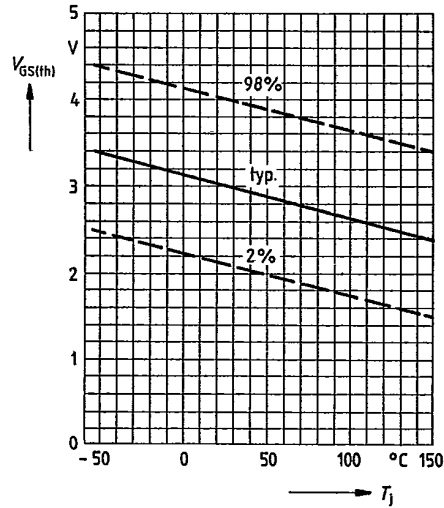
Typical transconductance  $g_{fs} = f(I_D)$

parameter: 80  $\mu\text{s}$  pulse test,  
 $V_{DS} = 25\text{V}$ ,  $T_J = 25^\circ\text{C}$



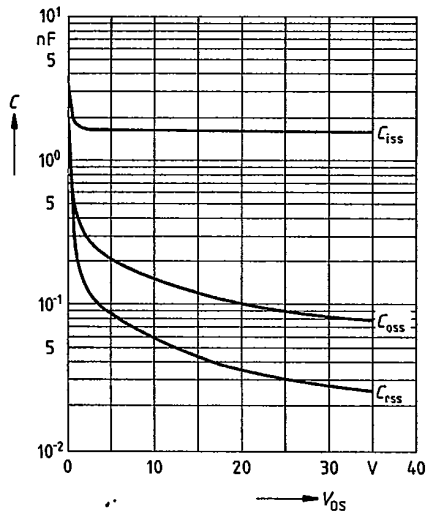
Gate threshold voltage  $V_{GS(th)} = f(T_J)$

parameter:  $V_{DS} = V_{GS}$ ,  $I_D = 1\text{mA}$   
(spread)

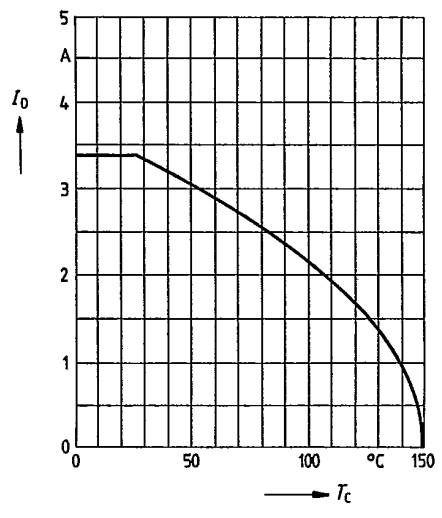


SIEMENS AKTIENGESELLSCHAFT

Typical capacitances  $C = f(V_{DS})$   
 parameter:  $V_{GS} = 0, f = 1\text{MHz}$

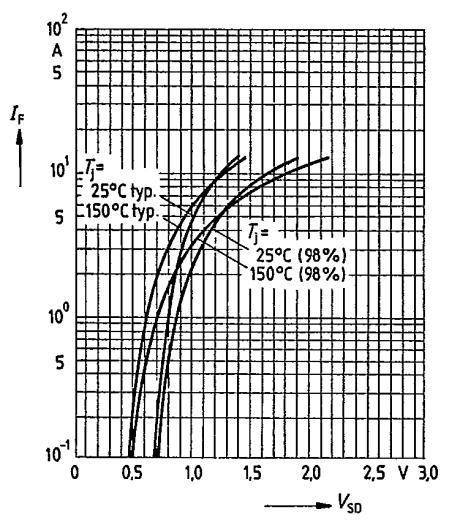


Continuous drain current  $I_D = f(T_C)$   
 parameter:  $V_{GS} \geq 10\text{V}$



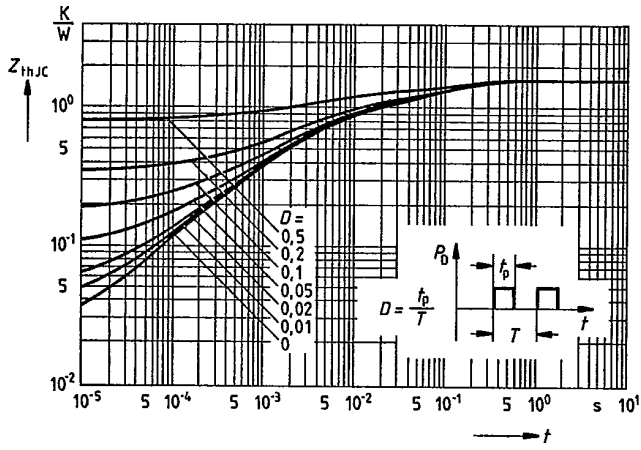
Forward characteristic of reverse diode

$I_F = f(V_{SD})$   
 parameter:  $T_j, t_p = 80 \mu\text{s}$   
 (spread)



SIEMENS AKTIENGESELLSCHAFT

Transient thermal impedance  $Z_{thJC} = f(t)$   
 parameter:  $D = t_p/T$



Typical gate-charge  $V_{GS} = f(Q_{Gate})$   
 parameter:  $I_D \text{ puls} = 5A$

